



Docket No.: H0498.70130US01  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Tao Deng  
Serial No.: 10/763,819  
Confirmation No.: 5026  
Filed: January 23, 2004  
For: FABRICATION OF METALLIC MICROSTRUCTURES VIA  
EXPOSURE OF PHOTORESISTIVE COMPOSITION  
Examiner: K. Duda  
Art Unit: 1756

**Certificate of Mailing Under 37 CFR 1.8(a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as First Class Mail, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: 4/11/07

Melanee Chwesard  
Signature

**AFTER ALLOWANCE UNDER 37 C.F.R. §1.312**

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Prior to issuance of the patent, applicant respectfully requests entry on this amendment under 37 C.F.R. 1.312 for the above-captioned patent application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.